

Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	60	V _P
Reverse Input Voltage	5	V
Input Control Voltage	15	V
Input Power Dissipation	225	mW
Total Power Dissipation ¹	800	mW
Isolation Voltage, Input to Output	2500	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 6.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

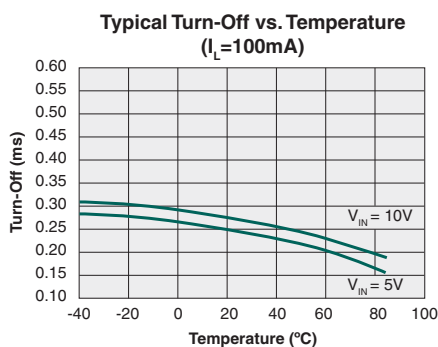
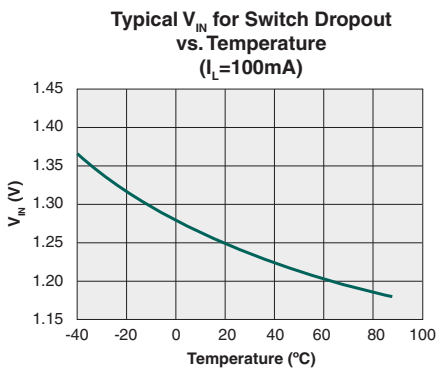
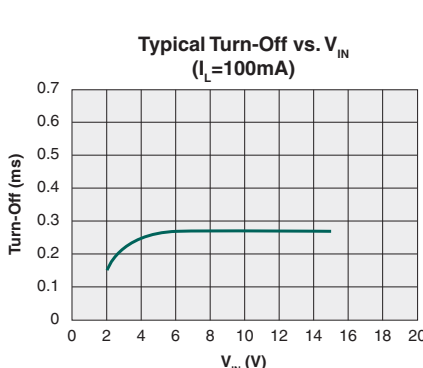
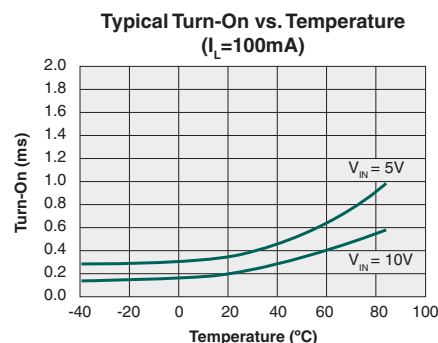
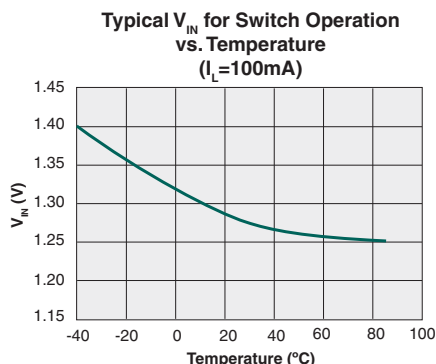
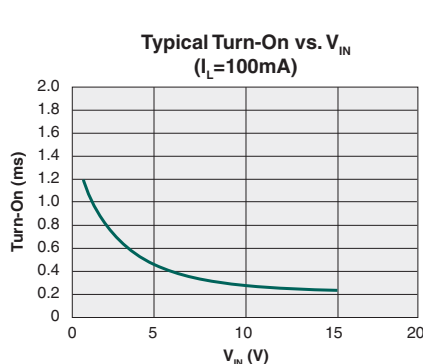
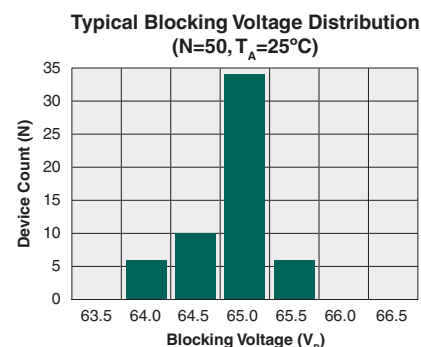
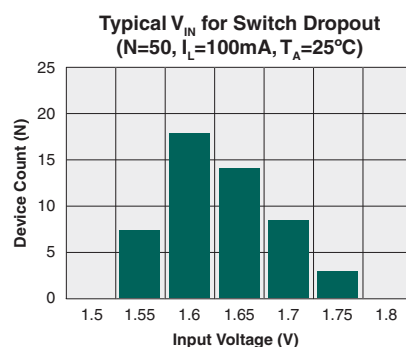
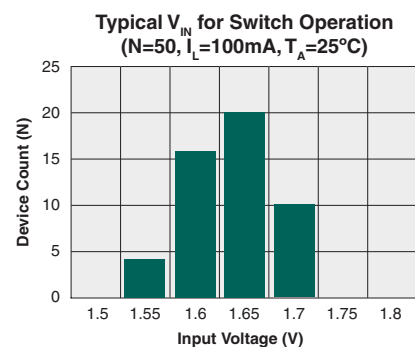
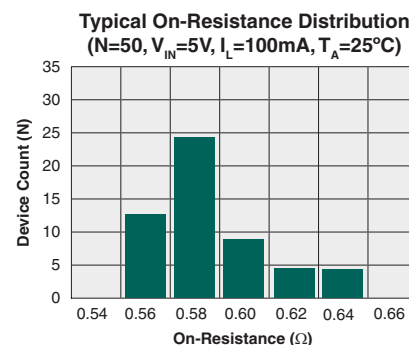
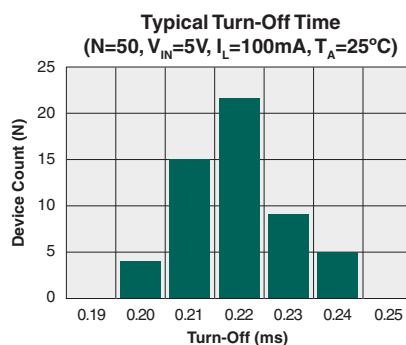
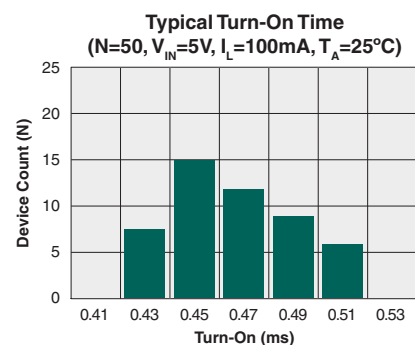
Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current						
Continuous ¹	V _{IN} =5V	I _L	-	-	600	mA _{rms} / mA _{DC}
Peak	t=10ms	I _{LPK}	-	-	±1	A _P
On-Resistance ²	I _L =600mA	R _{ON}	-	-	1.1	Ω
Off-State Leakage Current	V _L =60V _P	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	V _{IN} =5V, V _L =10V	t _{on}	-	-	5	ms
Turn-Off		t _{off}	-	-	5	
Output Capacitance	V _L =50V, f=1MHz	C _{OUT}	-	25	-	pF
Input Characteristics						
Input Control Voltage (must operate)	I _L =600mA	V _{OP}	-	-	3.75	V
Off Voltage (must be off)	-	V _{OFF}	1	-	-	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Input Resistor	-	-	900	1000	1100	Ω
Common Characteristics						
Capacitance, Input to Output	-	-	-	1	-	pF

¹ Load current derates linearly from 600mA @ 25°C to 480mA @ 80°C.

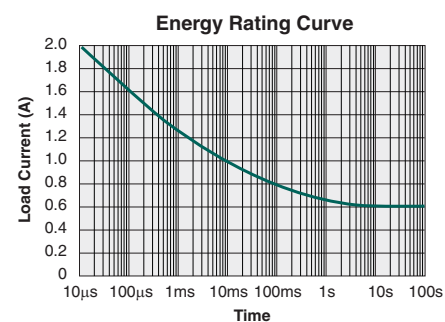
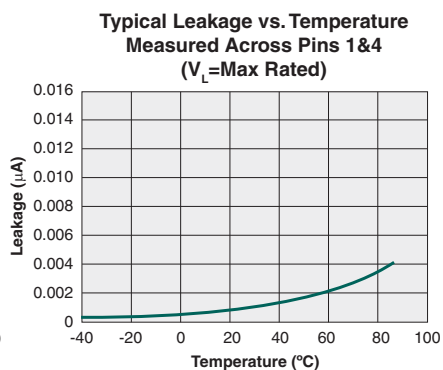
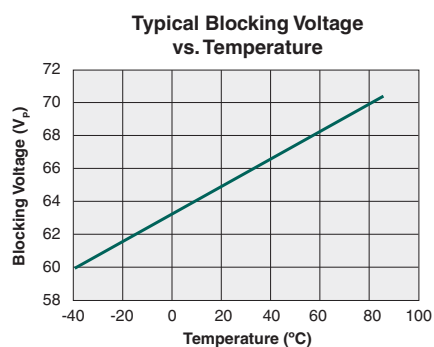
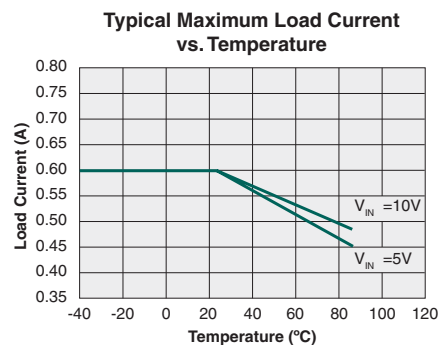
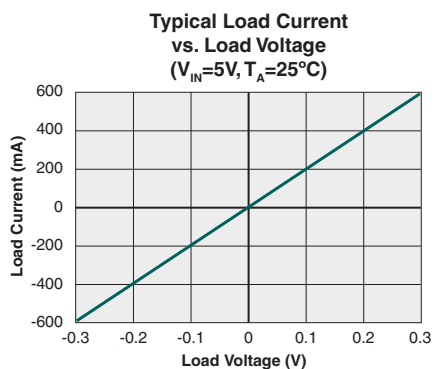
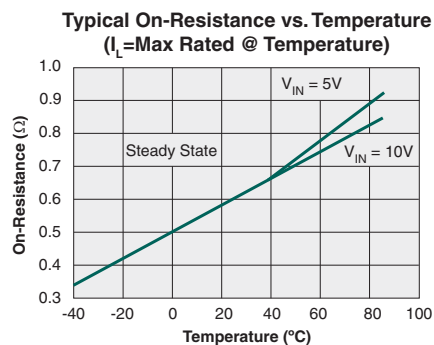
² Measurement taken within 1 second of on-time.

PERFORMANCE DATA*



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

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Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC1218Y	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
CPC1218Y	245°C for 30 seconds

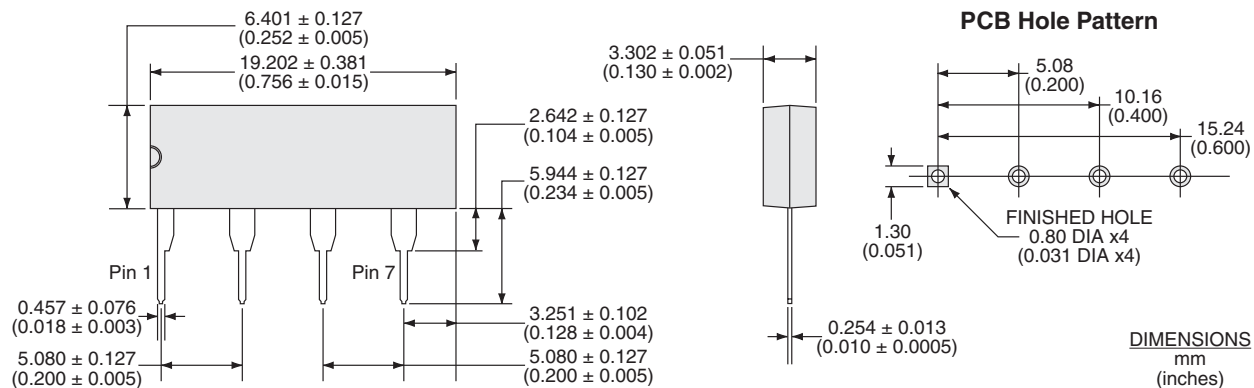
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.



MECHANICAL DIMENSIONS

CPC1218Y



For additional information please visit our website at: www.ixysic.com

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Specification: DS-CPC1218-R06
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